

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L5	21560	leadframe and holders and processing region and encapsulating	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 07:25
L6	21946	lead adj frame and holders and processing region and encapsulating	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 07:24
L7	3	lead adj frame and holders and processing near region and encapsulating	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 07:29
L8	1	leadframe and holders and processing near region and encapsulating and "29"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 07:26
L9	113	Wu near Jian .inv.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 07:27
L10	1	Wu near Jian .inv. and encapsulating near IC	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 07:28
L11	1	Wu near Jian .inv. and lead near frame and loading near device	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 07:28
L12	202	lead adj frame and IC and encapsulating and (257/692, 156/105 , 156/145 , 156/156 , 156/241 , 156/285 , 156/358 , 156/566 , 156/60 , 257/787 , 257/788 , 257/789 , 257/790 , 257/795 , 257/796 , 257/797 , 257/E21.503 , 438/107).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 07:29

L13	0	lead adj frame and IC and encapsulating and (257/692, 156/105 , 156/145 , 156/156 , 156/241 , 156/285 , 156/358 , 156/566 , 156/60 , 257/787 , 257/788 , 257/789 , 257/790 , 257/795 , 257/796 , 257/797 , 257/E21.503 , 438/107).ccls. and loading near device	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 07:30
L14	19	lead adj frame and IC and encapsulating and (257/692, 156/105 , 156/145 , 156/156 , 156/241 , 156/285 , 156/358 , 156/566 , 156/60 , 257/787 , 257/788 , 257/789 , 257/790 , 257/795 , 257/796 , 257/797 , 257/E21.503 , 438/107).ccls. and loading	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 07:30
L15	10	lead adj frame and IC and encapsulating and (257/795, 174/52.4 , 257/659 , 257/668 , 257/786 , 257/E21.499 , 257/E21.502 , 257/E23.189).ccls. and loading	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 07:32
L16	9	lead adj frame and IC and encapsulating and "29"/\$.ccls. and loading	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 07:32
L17	130	lead adj frame and IC and encapsulating and "29"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 07:35
L18	0	lead adj frame and IC and encapsulating and "29"/\$.ccls. and process near region	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 07:35
L19	50	lead adj frame and IC and encapsulating and "29"/\$.ccls. and processing	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 07:35